Since 1980

FLIP CHIP BONDER-A110

FLIP CHIP BONDER - A110

High Productivity

- 15,000 UPH (Based on Dry Run)

Mass Defect Protection Capability

- Flux, Die Tilt, Ejector Pin Missing, Contamination

Precision Bonding Capability

- ± 6μm @ 3σ

Thin Die / Small Die Capability

- Min. 40μm Thickness / Min. 0.4mm x 0.4mm

Semiconductor

FLIP CHIP BONDER
A110

Enhanced Machine Features

■ High Productivity

- 15,000 UPH (Based on Dry Run)
- Dual Bonding Head
- Hanmi Special Sequence Profile
- Enhanced Temperature Control System

■ Precision Bonding Capability

- ± 6μm @ 3σ
- Supreme Vision Inspection System
- High Accurate Gantry Structure
- Lower Vibration Control System
- One Casting Body Structure

■ Mass Defect Protection Capability

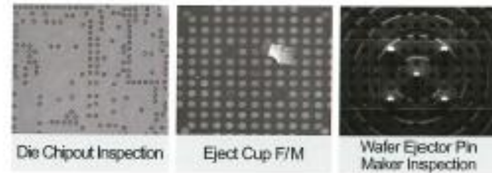
- Hanmi Special Flux Vision Inspection System
- Auto Flatness Check System
- Wafer Map Shift Prevent Function
- Foreign Material Detect Inspection System
- Ejector Pin Missing Inspection System
- Chip Out Detect Inspection System
- Multi Reject Mark Reading Capability

■ User Friendly & Easy Operation

- Windows Based HMI Screen
- Easy & Quick Conversion
- Easy Maintenance

"New Technology"
Flux Vision Inspection

Eject Cup F/M



Die Chipout Inspection | Eject Cup F/M | Wafer Ejector Pin Maker Inspection

Components and Substrates

Wafer	Die Size	0.4mm x 0.4mm
	Die Thickness	0.04mm ~ 3.0mm
	Wafer Size	up to 12"
Substrate	Width	28mm ~ 208mm
	Length	50mm ~ 300mm

Performance

Productivity	UPH	15,000 (Based on Dry Run)
Accuracy	X-Y Placement	± 6.0μm @ 3σ
	Chip Rotation (θ)	± 0.1 ˚@ 3σ
Bonding Head	Bonding Force	1N ~ 20N (Programmable from 1N)
Footprint	Cimension (W x D x H)	1,600mm x 1,200mm x 1,500mm
	Weight	2,700 kg

MTBA	2~5 hours
MTBF	168 hours
MTTA	3 minutes
MTTR	30 minutes

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